



UM61M512 Series

64K X 8, 3.3V I/O High Speed CMOS SRAM

Features

- Single +5V power supply
- Access times: 15/20 ns (max.)
- Current: Operating: 160mA (max.)
Standby: 10mA (max.)
- Full static operation, no clock or refreshing required
- 3.3V I/O compatible
- Directly TTL compatible: All inputs and outputs
- Common I/O using three-state output
- Output enable and two chip enable inputs for easy application
- Data retention voltage: 3V (min.)
- Available in 32-pin SKINNY DIP package

General Description

The UM61M512 is a low operating current 524,288-bit static random access memory organized as 65,536 words by 8 bits and operates on a single 5V power supply. It is built using UMC's high performance CMOS process.

Inputs and three-state outputs are TTL compatible and allow for direct interfacing with common system bus structures.

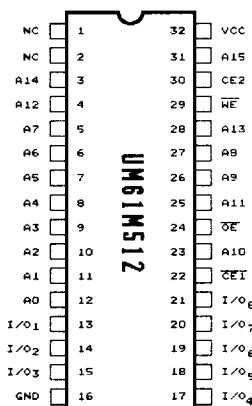
Special designed output circuitry allows for easy interfacing with 5V or 3V system bus and is ideal for mixed voltage system design.

Two chip enable inputs are provided for power down and device enable and an output enable input is included for easy interfacing.

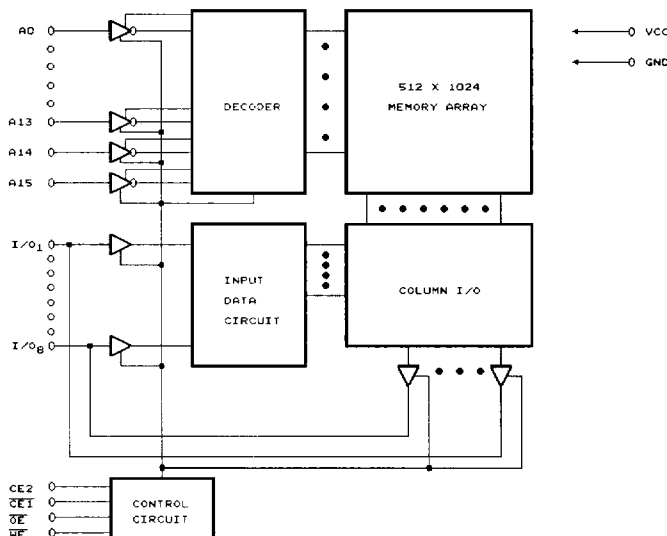
Data retention is guaranteed at power supply voltage as low as 3V.

High Speed
CMOS
SRAM

Pin Configuration



Block Diagram



Pin Description

Pin No.	Symbol	Description
3 - 12, 23, 25 - 28, 31	A0 - A15	Address Input
29	\overline{WE}	Write Enable
24	\overline{OE}	Output Enable
22	$\overline{CE1}$	Chip Enable
30	$\overline{CE2}$	Chip Enable
1, 2	NC	No Connection
13-15, 17-21	I/O ₁ - I/O ₈	Data Input/Output
32	VCC	Power Supply
16	GND	Ground

Recommended DC Operating Conditions

(T_A = 0°C to + 70°C)

Symbol	Parameter	Min.	Typ.	Max.	Unit
VCC	Supply Voltage	4.75	5.0	5.25	V
GND	Ground	0	0	0	V
V _{IH}	Input High Voltage	2.2	3.5	VCC + 0.3	V
V _{IL}	Input Low Voltage	-0.3	0	+0.8	V
C _L	Output Load	-	-	30	pF
TTL	Output Load	-	-	1	-

Absolute Maximum Ratings*

VCC to GND -0.5V to +7.0V
 IN, IN/OUT Volt to GND -0.5V to VCC +0.5V
 Operating Temperature, T_{opr} 0°C to +70°C
 Storage Temperature, T_{stg} -55°C to +125°C
 Temperature Under Bias, T_{bias} -10°C to +85°C
 Power Dissipation, P_T 1.0W
 Soldering Temp. & Time 260°C, 10 sec

***Comments**

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied and exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Electrical Characteristics (T_A = 0°C to + 70°C, VCC = 5V ± 5%, GND = 0V)

Symbol	Parameter	UM61M512-15/20		Unit	Conditions
		Min.	Max.		
I _{LI}	Input Leakage Current	-	2	μA	V _{IN} = GND to VCC
I _{LO}	Output Leakage Current	-	2	μA	$\overline{CE1}$ = V _{IH} or $\overline{CE2}$ = V _{IL} or \overline{OE} = V _{IH} or \overline{WE} = V _{IL} V _{I/O} = GND to VCC
I _{CC1} (1)	Dynamic Operating Current	-	160	mA	$\overline{CE1}$ = V _{IL} , $\overline{CE2}$ = V _{IH} I _{I/O} = 0 mA

DC Electrical Characteristics (continued)

Symbol	Parameter	UM61M512-15/20		Unit	Conditions
		Min.	Max.		
ISB	Standby Power Supply Current	–	30	mA	$\overline{CE1} = V_{IH}$ or $CE2 = V_{IL}$
ISB1		–	10	mA	$\overline{CE1} \geq V_{CC} - 0.2V$, $CE2 \geq V_{CC} - 0.2V$, $V_{IN} \geq V_{CC} - 0.2V$ or $V_{IH} \leq 0.2V$
ISB2		–	10	mA	$CE1 \leq 0.2V$, $CE2 \leq 0.2V$ $V_{IN} \geq V_{CC} - 0.2V$ or $V_{IN} \leq 0.2V$
VOL	Output Low Voltage	–	0.4	V	$I_{OL} = 8\text{ mA}$
VOH	Output High Voltage	2.4	3.3	V	$I_{OH} = -4\text{ mA}$ ($V_{CC} = 5V$)

Note: 1. I_{CC1} is dependent on output loading, cycle rates, and Read/Write patterns.

Truth Table

Mode	$\overline{CE1}$	$CE2$	\overline{OE}	\overline{WE}	I/O Operation	Supply Current
Standby	H	X	X	X	High Z	ISB, ISB1
	X	L	X	X	High Z	ISB, ISB2
Output Disable	L	H	H	H	High Z	I_{CC1}
Read	L	H	L	H	DOUT	I_{CC1}
Write	L	H	X	L	DIN	I_{CC1}

Note: X: H or L

Capacitance ($T_A = 25^\circ\text{C}$, $f = 1.0\text{ MHz}$)

Symbol	Parameter	Min.	Max.	Unit	Conditions
C_{IN}^*	Input Capacitance		8	pF	$V_{IN} = 0V$
$C_{I/O}^*$	Input/Output Capacitance		10	pF	$V_{I/O} = 0V$

* These parameters are sampled and not 100% tested.

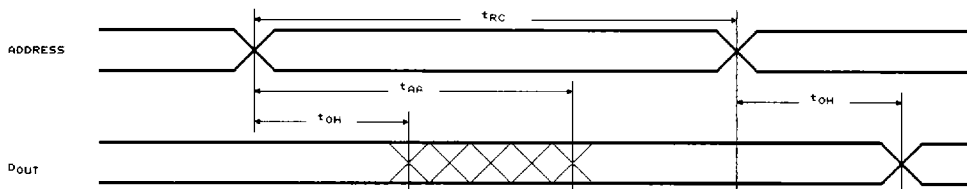
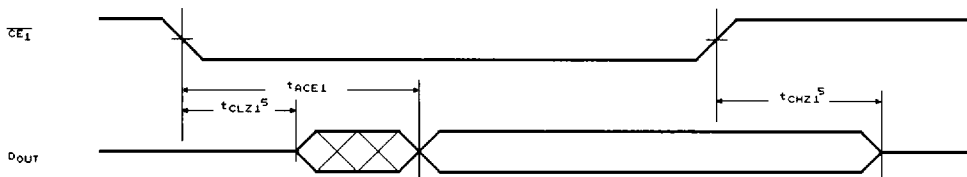
AC Characteristics ($T_A = 0^{\circ}\text{C}$ to $+70^{\circ}\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$)

Symbol	Parameter		UM61M512-15		UM61M512-20		Unit
			Min.	Max.	Min.	Max.	
Read Cycle							
t _{RC}	Read Cycle Time		15	–	20	–	ns
t _{AA}	Address Access Time		–	15	–	20	ns
t _{ACE1}	Chip Enable Access Time	CE1	–	15	–	20	ns
t _{ACE2}		CE2	–	15	–	20	ns
t _{OE}	Output Enable to Output Valid		–	7	–	9	ns
t _{CLZ1}	Chip Enable to Output in Low Z	CE1	5	–	5	–	ns
t _{CLZ2}		CE2	5	–	5	–	ns
t _{OLZ}	Output Enable to Output in Low Z		2	–	2	–	ns
t _{CHZ1}	Chip Disable to Output in High Z	CE1	–	10	–	10	ns
t _{CHZ2}		CE2	–	10	–	10	ns
t _{OHZ}	Output Disable to Output in High Z		2	9	2	9	ns
t _{OH}	Output Hold from Address Change		3	–	5	–	ns
Write Cycle							
t _{WC}	Write Cycle Time		15	–	20	–	ns
t _{CW}	Chip Enable to End of Write		12	–	15	–	ns
t _{AS}	Address Setup Time of Write		0	–	0	–	ns
t _{AW}	Address Valid to End of Write		12	–	15	–	ns

AC Characteristics (continued)

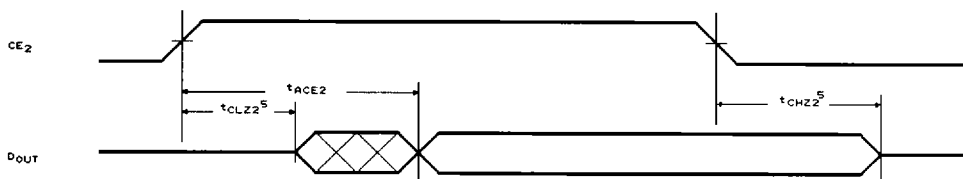
Symbol	Parameter	UM61M512-15		UM61M512-20		Unit
		Min.	Max.	Min.	Max.	
t_{WP}	Write Pulse Width	9	–	11	–	ns
t_{WR}	Write Recovery Time	0	–	0	–	ns
t_{WHZ}	Write to Output in High Z	0	8	0	13	ns
t_{DW}	Data to Write Time Overlap	7	–	7	–	ns
t_{DH}	Data Hold from Write Time	0	–	0	–	ns
t_{OW}	Output Active from End of Write	5	–	5	–	ns

Notes: t_{CHZ1} , t_{CHZ2} , t_{OH} and t_{WHZ} are defined as the time at which the outputs achieve the open circuit condition and are not referred to output voltage levels.

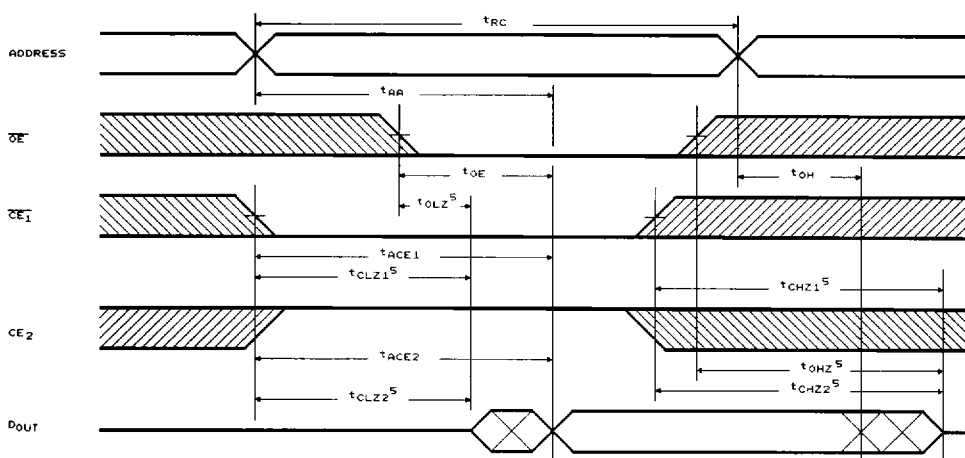
Timing Waveforms
Read Cycle 1 (1, 2, 4)

Read Cycle 2 (1, 3, 4, 6)


Timing Waveforms (continued)

Read Cycle 3^(1, 4, 7, 8)



Read Cycle 4⁽¹⁾

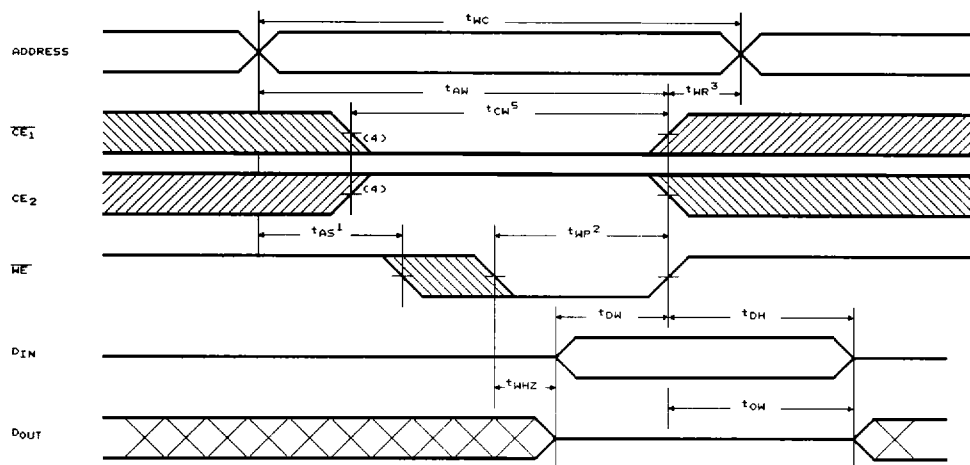


- Notes:
1. WE is high for Read Cycle.
 2. Device is continuously enabled $\overline{CE1} = V_{IL}$ and $CE2 = V_{IH}$.
 3. Address valid prior to or coincident with $\overline{CE1}$ transition low.
 4. $\overline{OE} = V_{IL}$.
 5. Transition is measured $\pm 500\text{mV}$ from steady state. This parameter is sampled and not 100% tested.
 6. $CE2$ is high.
 7. $\overline{CE1}$ is low.
 8. Address valid prior to or coincident with $CE2$ transition high.

Timing Waveforms (continued)

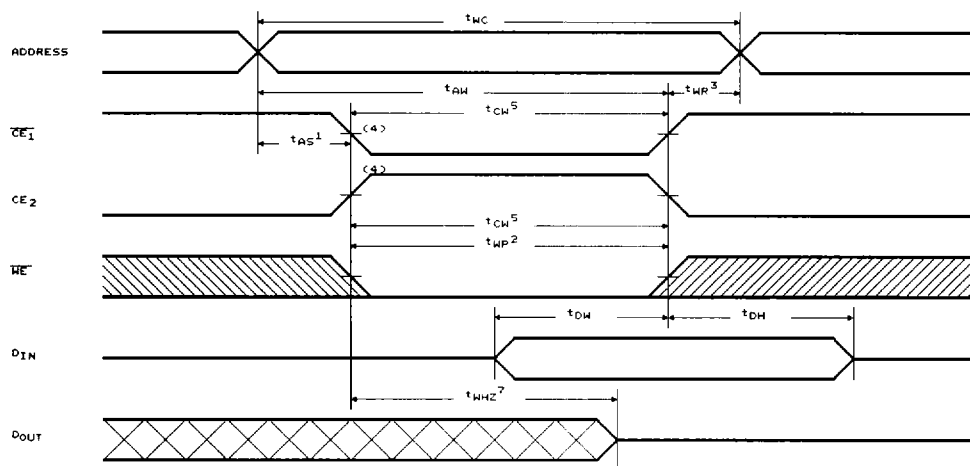
Write Cycle 1⁽⁶⁾

(Write Enable Controlled)



Write Cycle 2

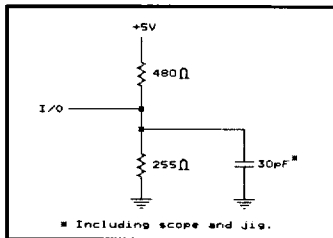
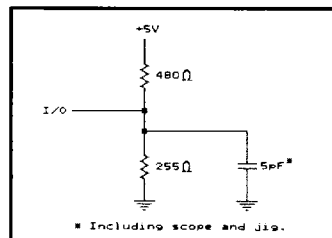
(Chip Enable Controlled)



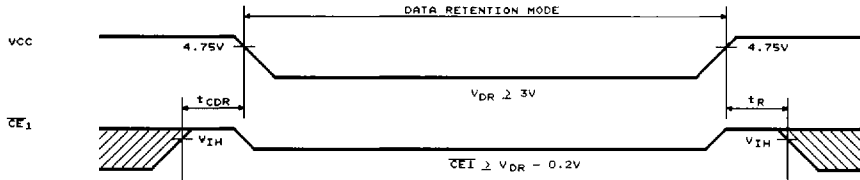
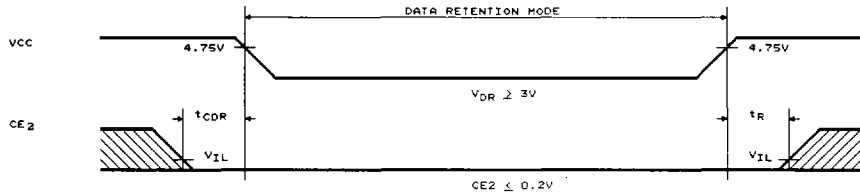
- Notes:
1. t_{AS} is measured from the address valid to the beginning of Write.
 2. A Write occurs during the overlap (t_{WP}) of a low $\overline{CE1}$, a high $\overline{CE2}$ and a low \overline{WE} .
 3. t_{WR} is measured from the earliest of $\overline{CE1}$ or \overline{WE} going high or $\overline{CE2}$ going low to the end of the Write cycle.
 4. If the $\overline{CE1}$ low transition or the $\overline{CE2}$ high transition occurs simultaneously with the \overline{WE} low transition or after the \overline{WE} transition, outputs remain in a high impedance state.
 5. t_{CW} is measured from the later of \overline{CE} going low or $\overline{CE2}$ going high to the end of Write.
 6. \overline{OE} is continuously low. ($\overline{OE} = V_{IL}$)
 7. Transition is measured $\pm 500\text{mV}$ from steady state. This parameter is sampled and not 100% tested.

AC Test Conditions

Input Pulse Levels	0V to 3.0V
Input Rise and Fall Time	5 ns
Input and Output Timing Reference Levels	1.5V
Output Load	See Fig. 1, 2


Figure 1. Output Load

Figure 2. Output Load for t_{CLZ1} , t_{CLZ2} , t_{OLZ} , t_{CHZ1} , t_{CHZ2} , t_{OHZ} , t_{WHZ} , and t_{OW}
Data Retention Characteristics ($T_A = 0^\circ\text{C}$ to 70°C)

Symbol	Parameter	Min.	Max.	Unit	Conditions
V_{DR1}	VCC for Data Retention	3	5.25	V	$CE1 \geq VCC - 0.2V$ $CE2 \geq VCC - 0.2V$ or $CE2 \leq 0.2V$
V_{DR2}		3	5.25	V	$CE2 \leq 0.2V$ $CE1 \geq VCC - 0.2V$ or $CE1 \leq 0.2V$
I_{CCDR1}	Data Retention Current	—	5	mA	$VCC = 3.0V$ $CE1 \geq VCC - 0.2V$ $CE2 \geq VCC - 0.2V$ $V_{IN} \geq VCC - 0.2V$ or $V_{IN} \leq 0.2V$
I_{CCDR2}		—	5	mA	$VCC = 3.0V$ $CE2 \leq 0.2V$ $CE1 \leq 0.2V$ $V_{IN} \geq VCC - 0.2V$ or $V_{IN} \leq 0.2V$
t_{CDR}	Chip Disable to Data Retention Time	0	—	ns	See Retention Waveform
t_R	Operation Recovery Time	5	—	ms	

Low VCC Data Retention Waveform (1) (CE1 Controlled)

Low VCC Data Retention Waveform (2) (CE2 Controlled)

Ordering Information

Part No.	Access Time (ns)	Operating Current Max. (mA)	Standby Current Max. (mA)	Package
UM61M512K-15	15	160	10	32L SKINNY
UM61M512K-20	20	160	10	32L SKINNY